



Material Content Data Sheet



Sales Product Name	BSC079N03LSC G			Issued		11. December 2019			
MA#	MA001620152								
Package	PG-TDSON-8-40			Weight*		111.53 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.709	0.64	0.64	6356	6356	
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		131		
	non noble metal	iron	7439-89-6	0.049	0.04		437		
	non noble metal	copper	7440-50-8	48.649	43.63	43.68	436214	436782	
wire	non noble metal	copper	7440-50-8	0.059	0.05	0.05	528	528	
encapsulation	organic material	carbon black	1333-86-4	0.085	0.08		760		
	plastics	epoxy resin	-	6.698	6.01		60057		
	inorganic material	silicondioxide	60676-86-0	35.610	31.93	38.02	319292	380109	
leadfinish	non noble metal	tin	7440-31-5	1.520	1.36	1.36	13629	13629	
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1421	1421	
solder	non noble metal	tin	7440-31-5	0.021	0.02		187		
	noble metal	silver	7440-22-4	0.026	0.02		234		
	non noble metal	lead	7439-92-1	0.996	0.89	0.93	8932	9353	
heat sink clip	inorganic material	phosphorus	7723-14-0	0.005	0.00		46		
	non noble metal	iron	7439-89-6	0.017	0.02		152		
	non noble metal	copper	7440-50-8	16.910	15.16	15.18	151624	151822	
*deviation	< 10%				Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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